

Original document

IC TAG STRUCTURE

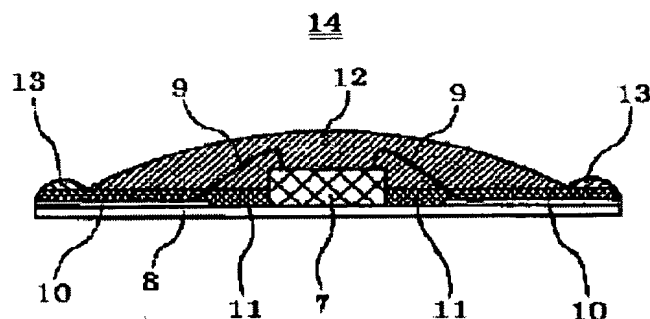
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Abstract of JP2001014442

PROBLEM TO BE SOLVED: To make an IC tag into structure, which is easily destroyed in the case of releasing the IC tag so as to completely disable recycling.

SOLUTION: In the IC tag structure, an IC module part 14, where an IC chip 7 is mounted on a substrate 8 having a pattern part 10, the IC chip 7 and the pattern part on the substrate are connected by wire bonding and the IC chip and wire part are sealed by sealing resin, and a coil-shaped copper wire to be an antenna are provided and the IC module part and the coil-shaped copper wire are sandwiched between film members having adhesive agent, in such a case, a release layer 11 is provided between the sealing resin for sealing the IC chip 7 and the substrate 8.



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